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United States Patent [19]

Schnur et al.

[11] **Patent Number:** 5,079,600[45] **Date of Patent:** Jan. 7, 1992[54] **HIGH RESOLUTION PATTERNING ON SOLID SUBSTRATES**

[76] **Inventors:** Joel M. Schnur, 6009 Lincolnwood Ct., Burke, Va. 22015; Paul E. Schoen, 5006 Taney Ave., Alexandria, Va. 22304; Martin C. Peckerar, 12917 Buccaneer Rd., Silver Spring, Md. 20904; Christie R. K. Marrian, 6805 Kenyon Dr., Alexandria, Va. 22307; Jeffrey M. Calvert, 6033 Wilmington Dr., Burke, Va. 22015; Jacque H. Georger, Jr., 8409 Great Lake Rd., Springfield, Va. 22153

[21] **Appl. No.:** 182,123[22] **Filed:** Apr. 14, 1988**Related U.S. Application Data**

[63] Continuation-in-part of Ser. No. 022,439, Mar. 6, 1987.

[51] **Int. Cl.⁵** H01L 27/12; B05D 5/12[52] **U.S. Cl.** 357/4; 357/23.7; 427/54.1; 427/98[58] **Field of Search** 428/546; 427/96-98, 427/54.1; 357/4, 23.7[56] **References Cited****U.S. PATENT DOCUMENTS**

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Primary Examiner—Peter A. Nelson*Attorney, Agent, or Firm*—Wolf, Greenfield & Sacks[57] **ABSTRACT**

A process for producing metal plated paths on a solid substrate of the kind which has polar functional groups at its surface, utilizing a self-assembling film that is chemically absorbed on the substrate's surface. The solid substrate may, for example, be an insulator of the kind used for substrates in printed circuitry or may, as another example, be a semiconductor of the kind used in semiconductor microcircuitry. The chemical reactivity in regions of the ultra-thin film is altered to produce a desired pattern in the film. A catalytic precursor which adheres only to those regions of the film having enough reactivity to bind the catalyst is applied to the film's surface. The catalyst coated structure is then immersed in an electroless plating bath where metal plates onto the regions activated by the catalyst.

34 Claims, 2 Drawing Sheets